

Ultra High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment*

DIGI-KEY PART # **ATS1034-ND**

ATS PART # ATS-50210P-C2-R0

Features & Benefits

maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling

maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB

Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards

Comes preassembled with high performance, phase changing, thermal interface material

Designed for standard height components from 3 to 4.5mm



Thermal Performance Table

| AIR VELOCITY | | THERMAL RESISTANCE | |
|--------------|-----|--------------------|---------------|
| FT/MIN | M/S | °C/W (UNDUCTED) | °C/W (DUCTED) |
| 200 | 1.0 | 5.4 | 4.3 |
| 300 | 1.5 | 4.4 | |
| 400 | 2.0 | 3.9 | |
| 500 | 2.5 | 3.5 | |
| 600 | 3.0 | 3.2 | |
| 700 | 3.5 | 3 | |
| 800 | 4.0 | 2.8 | |

Product Details†

| DIMENSION A | DIMENSION B | DIMENSION C§ | DIMENSION D | TIM† | FINISH |
|-------------|-------------|--------------|-------------|--------|---------------|
| 21 | 21 | 17.5 | 38.16 | C1100F | BLUE-ANODIZED |

For further technical information, please contact Advanced Thermal Solutions, Inc. at **1-781-769-2800** or www.qats.com

* RoHS Compliant

‡ TIM = Thermal Interface Material

† Dimensions are measured in millimeters

◆ Dimensions A & B refer to component size

§ Dimension C = the height of the heat sink shown above and does not include the height of the attachment method



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Innovations in Thermal Management®



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